Latch/flip-flop | 74F373/74F374

74F373 Octal transparent latch (3-State)
74F374 Octal D flip-flop (3-State)

FEATURES

- 8–bit transparent latch–74F373
- 8–bit positive edge triggered register–74F374
- 3–state outputs glitch free during power–up and power–down
- Common 3–state output register
- Independent register and 3–state buffer operation

DESCRIPTION

The 74F373 is an octal transparent latch coupled to eight 3–state output devices. The two sections of the device are controlled independently by enable (E) and output enable ($\overline{OE}$) control gates.

The data on the D inputs is transferred to the latch outputs when the enable (E) input is high. The latch remains transparent to the data input while E is high, and stores the data that is present one setup time before the high–to–low enable transition.

The 3–state output buffers are designed to drive heavily loaded 3–state busses, MOS memories, or MOS micrprocessors.

The active low output enable ($\overline{OE}$) controls all eight 3–state buffers independent of the latch operation. When $\overline{OE}$ is low, latched or transparent data appears at the output.

When $\overline{OE}$ is high, the outputs are in high impedance "off" state, which means they will neither drive nor load the bus.

The 74F374 is an 8–bit edge triggered register coupled to eight 3–state output buffers. The two sections of the device are controlled independently by clock (CP) and output enable ($\overline{OE}$) control gates.

The register is fully edge triggered. The state of the D input, one setup time before the low–to–high clock transition is transferred to the corresponding flip–flop's Q output.

The 3–state output buffers are designed to drive heavily loaded 3–state busses, MOS memories, or MOS microprocessors.

The active low output enable ($\overline{OE}$) controls all eight 3–state buffers independent of the register operation. When $\overline{OE}$ is low, the data in the register appears at the outputs. When $\overline{OE}$ is high, the outputs are in high impedance "off" state, which means they will neither drive nor load the bus.

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F373	4.5ns	35mA

TYPE	TYPICAL f_{max}	TYPICAL SUPPLY CURRENT (TOTAL)
74F374	165MHz	55mA

ORDERING INFORMATION

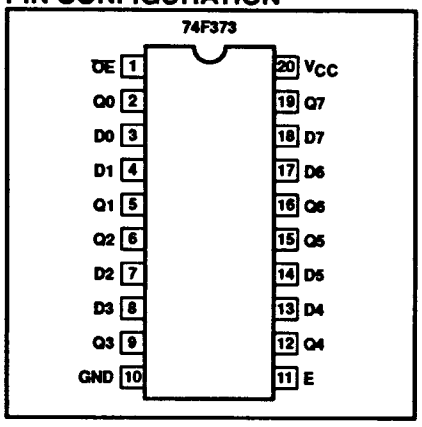
DESCRIPTION	ORDER CODE
	COMMERCIAL RANGE V_{CC} = 5V ±10%, T_{amb} = 0°C to +70°C
20–pin plastic DIP	N74F373N, N74F374N
20–pin plastic SOL	N74F373D, N74F374D

INPUT AND OUTPUT LOADING AND FAN OUT TABLE

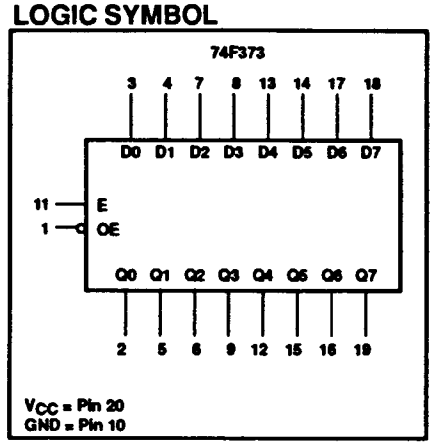
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
D0 – D7	Data inputs	1.0/1.0	20µA/0.6mA
E (74F373)	Enable input (active high)	1.0/1.0	20µA/0.6mA
$\overline{OE}$	Output enable inputs (active low)	1.0/1.0	20µA/0.6mA
CP (74F374)	Clock pulse input (active rising edge)	1.0/1.0	20µA/0.6mA
Q0 – Q7	3–state outputs	150/40	3.0mA/24mA

NOTE: One (1.0) FAST unit load is defined as: 20µA in the high state and 0.6mA in the low state.

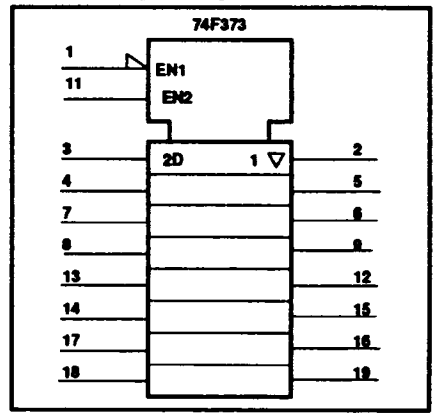
PIN CONFIGURATION



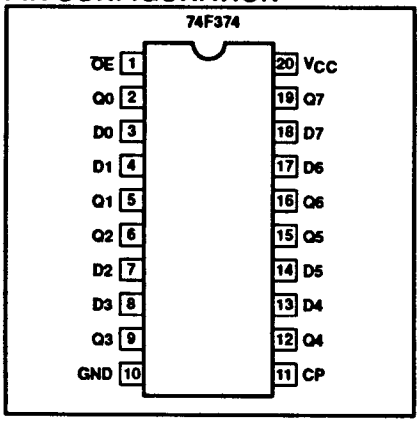
LOGIC SYMBOL



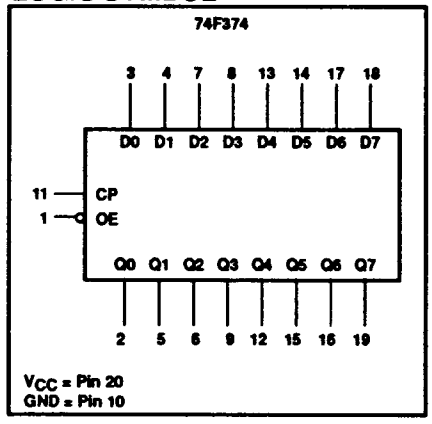
IEC/IEEE SYMBOL



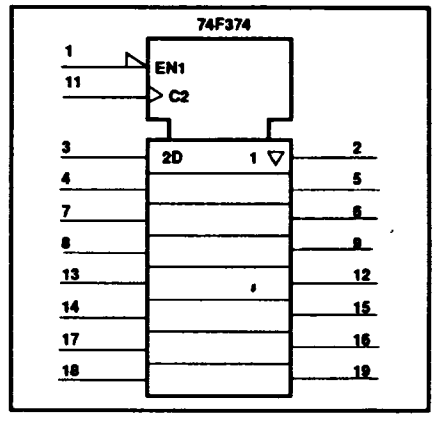
PIN CONFIGURATION



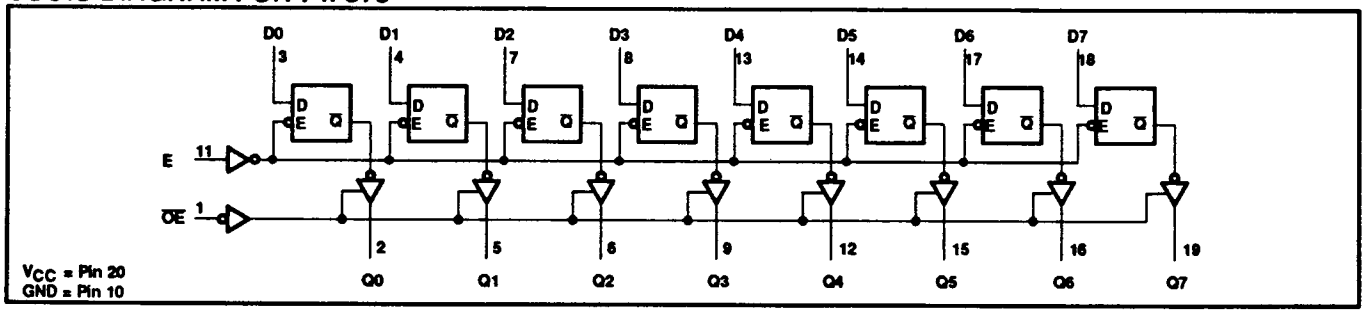
LOGIC SYMBOL



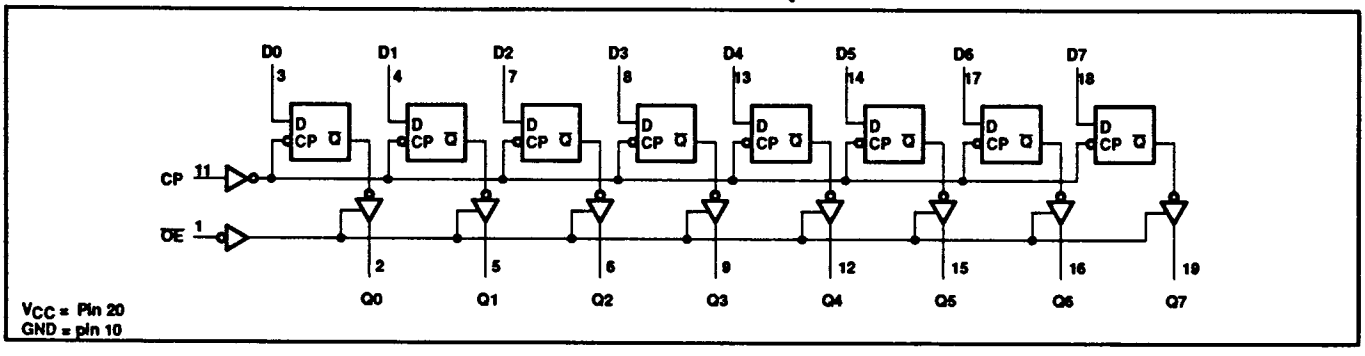
IEC/IEEE SYMBOL



LOGIC DIAGRAM FOR 74F373



LOGIC DIAGRAM FOR 74F374



FUNCTION TABLE FOR 74F373

INPUTS			INTERNAL	OUTPUTS	OPERATING MODE
$\overline{OE}$	E	Dn	REGISTER	Q0 – Q7	
L	H	L	L	L	Enable and read register
L	H	H	H	H	
L	↓	l	L	L	Latch and read register
L	↓	h	H	H	
L	L	X	NC	NC	Hold
H	L	X	NC	Z	Disable outputs
H	H	Dn	Dn	Z	

NOTES:
3. H = High–voltage level
4. h = High state must be present one setup time before the high–to–low enable transition
5. L = Low–voltage level
6. l = Low state must be present one setup time before the high–to–low enable transition
7. NC = No change
8. X = Don't care
9. Z = High impedance "off" state
10. ↓ = High–to–low enable transition

FUNCTION TABLE FOR 74F374

INPUTS			INTERNAL	OUTPUTS	OPERATING MODE
$\overline{OE}$	CP	Dn	REGISTER	Q0 – Q7	
L	↑	l	L	L	Load and read register
L	↑	h	H	H	
L	↕	X	NC	NC	Hold
H	↕	X	NC	Z	Disable outputs
H	↑	Dn	Dn	Z	

NOTES:
1. H = High–voltage level
2. h = High state must be present one setup time before the low–to–high clock transition
3. L = Low–voltage level
4. l = Low state must be present one setup time before the low–to–high clock transition
5. NC = No change
6. X = Don't care
7. Z = High impedance "off" state
8. ↑ = Low–to–high clock transition
9. ↕ = Not low–to–high clock transition

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V_{CC}	Supply voltage	–0.5 to +7.0	V
V_{IN}	Input voltage	–0.5 to +7.0	V
I_{IN}	Input current	–30 to +5	mA
V_{OUT}	Voltage applied to output in high output state	–0.5 to V_{CC}	V
I_{OUT}	Current applied to output in low output state	48	mA
T_{amb}	Operating free air temperature range	0 to +70	°C
T_{stg}	Storage temperature range	–65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS			UNIT
		MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5.0	5.5	V
V_{IH}	High–level input voltage	2.0			V
V_{IL}	Low–level input voltage			0.8	V
I_{IK}	Input clamp current			–18	mA
I_{OH}	High–level output current			–3	mA
I_{OL}	Low–level output current			24	mA
T_{amb}	Operating free air temperature range	0		+70	°C

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER		TEST CONDITIONS[1]		LIMITS			UNIT
					MIN	TYP[2]	MAX	
V_{OH}	High-level output voltage		V_{CC} = MIN, V_{IL} = MAX,	±10%V_{CC}	2.4			V
			V_{IH} = MIN, I_{OH} = MAX	±5%V_{CC}	2.7	3.4		V
V_{OL}	Low-level output voltage		V_{CC} = MIN, V_{IL} = MAX,	±10%V_{CC}		0.35	0.50	V
			V_{IH} = MIN, I_{OL} = MAX	±5%V_{CC}		0.35	0.50	V
V_{IK}	Input clamp voltage		V_{CC} = MIN, I_I = I_{IK}			–0.73	-1.2	V
I_I	Input current at maximum input voltage		V_{CC} = MAX, V_I = 7.0V				100	µA
I_{IH}	High–level input current		V_{CC} = MAX, V_I = 2.7V				20	µA
I_{IL}	Low–level input current		V_{CC} = MAX, V_I = 0.5V				–0.6	mA
I_{OZH}	Off–state output current, high–level voltage applied		V_{CC} = MAX, V_O = 2.7V				50	µA
I_{OZL}	Off–state output current, low–level voltage applied		V_{CC} = MAX, V_O = 0.5V				–50	µA
I_{OS}	Short–circuit output current3		V_{CC} = MAX		-60		-150	mA
I_{CC}	Supply current (total)	74F373	V_{CC} = MAX			35	60	mA
		74F374				57	86	mA

NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
2. All typical values are at V_{CC} = 5V, T_{amb} = 25°C.
3. Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

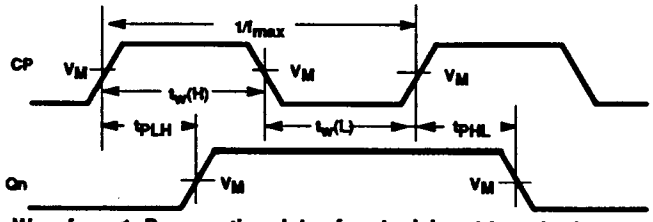
AC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER		TEST CONDITION	LIMITS					UNIT
				T_{amb} = +25°C, V_{CC} = +5.0V, C_L = 50pF, R_L = 500Ω			T_{amb} = 0°C to +70°C, V_{CC} = +5.0V ± 10%, C_L = 50pF, R_L = 500Ω		
				MIN	TYP	MAX	MIN	MAX	
t_{PLH} t_{PHL}	Propagation delay Dn to Qn	74F373	Waveform 3	3.0 2.0	5.3 3.7	7.0 5.0	3.0 2.0	8.0 6.0	ns
t_{PLH} t_{PHL}	Propagation delay E to Qn		Waveform 2	5.0 3.0	9.0 4.0	11.5 7.0	5.0 3.0	12.0 8.0	ns
t_{PZH} t_{PZL}	Output enable time to high or low level		Waveform 6 Waveform 7	2.0 2.0	5.0 5.6	11.0 7.5	2.0 2.0	11.5 8.5	ns
t_{PHZ} t_{PLZ}	Output disable time from high or low level		Waveform 6 Waveform 7	2.0 2.0	4.5 3.8	6.5 5.0	2.0 2.0	7.0 6.0	ns
f_{max}	Maximum clock frequency	74F374	Waveform 1	150	165		140		ns
t_{PLH} t_{PHL}	Propagation delay CP to Qn		Waveform 1	3.5 3.5	5.0 5.0	7.5 7.5	3.0 3.0	8.5 8.5	ns
t_{PZH} t_{PZL}	Output enable time to high or low level		Waveform 6 Waveform 7	2.0 2.0	9.0 5.3	11.0 7.5	2.0 2.0	12.0 8.5	ns
t_{PHZ} t_{PLZ}	Output disable time from high or low level		Waveform 6 Waveform 7	2.0 2.0	5.3 4.3	6.0 5.5	2.0 2.0	7.0 6.5	ns

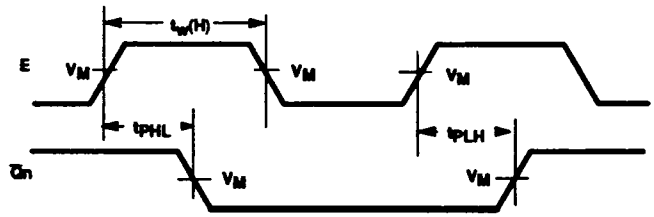
AC SETUP REQUIREMENTS

SYMBOL	PARAMETER		TEST CONDITION	LIMITS					UNIT
				T_{amb} = +25°C, V_{CC} = +5.0V, C_L = 50pF, R_L = 500Ω			T_{amb} = 0°C to +70°C, V_{CC} = +5.0V ± 10%, C_L = 50pF, R_L = 500Ω		
				MIN	TYP	MAX	MIN	MAX	
t_{su} (H) t_{su} (L)	Setup time, high or low level Dn to E	74F373	Waveform 4	0 1.0			0 1.0		ns
t_h (H) t_h (L)	Hold time, high or low level Dn to E		Waveform 4	3.0 3.0			3.0 3.0		ns
t_w (H)	E Pulse width, high		Waveform 1	3.5			4.0		ns
t_{su} (H) t_{su} (L)	Setup time, high or low level Dn to CP	74F374	Waveform 5	2.0 2.0			2.0 2.0		ns
t_h (H) t_h (L)	Hold time, high or low level Dn to CP		Waveform 5	0 0			0 0		ns
t_w (H) t_w (L)	CP Pulse width, high or low		Waveform 5	3.5 4.0			3.5 4.0		ns

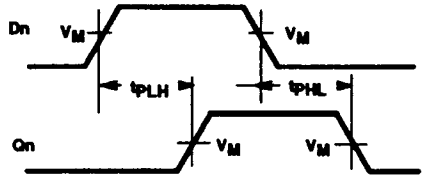
AC WAVEFORMS



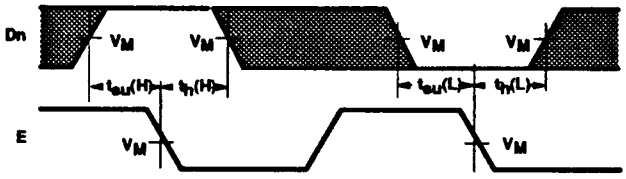
Waveform 1. Propagation delay for clock input to output, clock pulse widths, and maximum clock frequency



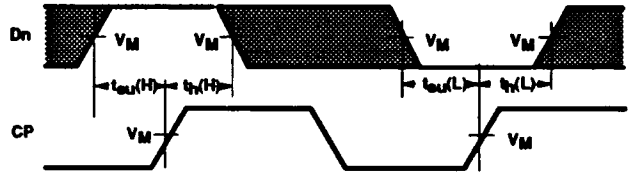
Waveform 2. Propagation delay for enable to output and enable pulse width



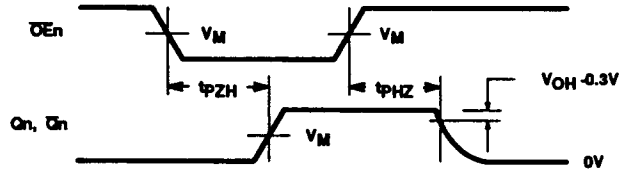
Waveform 3. Propagation delay for data to output



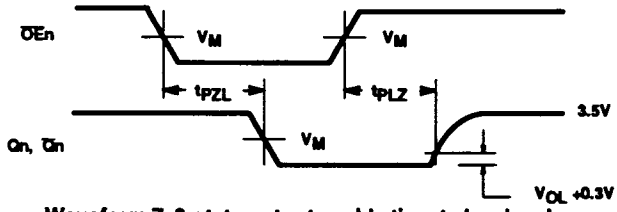
Waveform 4. Data setup time and hold times



Waveform 5. Data setup time and hold times



Waveform 6. 3-state output enable time to high level and output disable time from high level



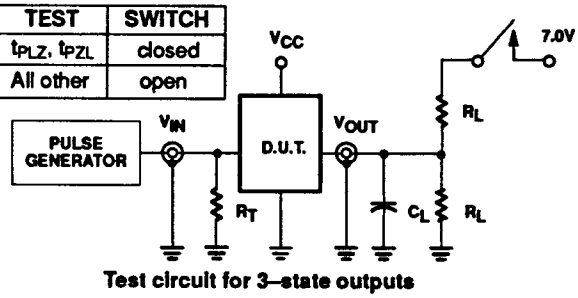
Waveform 7. 3-state output enable time to low level and output disable time from low level

NOTES:
1. For all waveforms, V_M = 1.5V.
2. The shaded areas indicate when the input is permitted to change for predictable output performance.

TEST CIRCUIT AND WAVEFORMS

SWITCH POSITION

TEST	SWITCH
t_{PLZ}, t_{PZL}	closed
All other	open



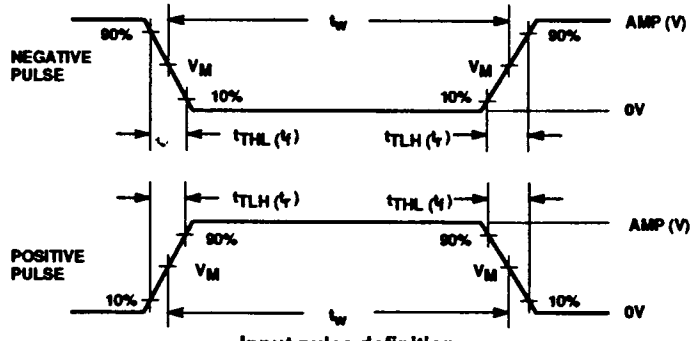
Test circuit for 3-state outputs

DEFINITIONS:

R_L = Load resistor; see AC electrical characteristics for value.

C_L = Load capacitance includes jig and probe capacitance; see AC electrical characteristics for value

R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.



Input pulse definition

family	INPUT PULSE REQUIREMENTS					
	amplitude	V_M	rep. rate	t_w	t_{TLH}	t_{THL}
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns

VI. COMMERCIAL PRODUCT SPECIAL PROCESSING T-90-20

SUPR II LEVEL B

Signetics Upgraded Product Reliability (SUPR) program is designed to provide customers whose systems require an infant mortality level less than that of our non-burned-in products (which is typically below 1000 PPM).

DEVICE AVAILABILITY

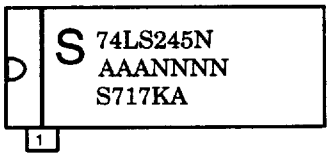
Products available for Level B processing are identified in the Price Book with a "B" suffix to the basic part number.

SUPR II LEVEL B PRICING ADDERS

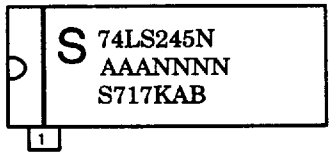
PRODUCT FAMILY	SUGGESTED RESALE ADDERS 1–99	100–999	OVER 1000
LIN	.14	.14	.11
LOG (TTL)			
(SSI)	.12	.10	.08
(MSI)	.16	.14	.11
(OCT)	.16	.14	.11
(CTM)	.16	.14	.11
LOG (ECL)			
(SSI)	.25	.23	.20
(MSI)	.25	.23	.20
LOG (LSI) (RAM) MIC (8X)	Consult Factory for Pricing		
PLD	Consult Factory for Pricing		
MCG	Consult Factory for Pricing		
DAT MIC	Not Available		

MARKING FORMAT EXAMPLES

Standard (no Burn-In) Products (Dual-in-line)



SUPR II (Burned-In) Products (Dual-in-line)



NOTE: The "B" in the 7th position on the 3rd line, when present, is the SUPR II Burn-In indicator.

TAPE AND REEL PACKAGING

SPECIFICATIONS

Tape and Reel specifications conform to Electronic Industries Association (EIA) Proposed Specification #EIA-481-A using 13 inch reels. Current incremental quantities reflect the quantities per reel. As more customers are able to handle a larger quantity per reel, this quantity will be increased.

DEVICE AVAILABILITY

Products available in tape and reel packaging are identified in the Price Book with a "T" suffix to the basic part number and are only offered as a product for sale by the reel. Return of product is limited to full reels with unbroken quality seals.

TAPE AND REEL PRICING ADDERS

PRODUCT FAMILY	SUGGESTED RESALE ADDER
MCG	.07
LIN	.07
LOG	.07
DAT MIC	PACKAGE A28 = .20 A44 = .25 A52 = .30 A68 = .40 A84 = .45 D24 = .17

VII. PACKING QUANTITY INFORMATION

T-90-20

CERAMIC DUAL IN-LINE (CERDIP)

PACKAGE CODE	PIN COUNT	QUANTITIES	
		DEVICES PER TUBE	DEVICES PER BOX
F/FE, BPA, PA	8-pin (300-mil)	48	1920
F, BCA, CA	14-pin (300-mil)	25	1000
F, BEA, EA	16-pin (300-mil)	25	1000
F, BVA, MVA	18-pin (300-mil)	21	840
F/FA, BRA, RA	20-pin (300-mil)	20	800
F, BWA, WA	22-pin (400-mil)	17	544
F/FA/F6, BJA, JA	24-pin (600-mil)	15	360
F/FA/F3/F24, BLA, LA	24-pin (300-mil)	15	600
F, BXA, XA	24-pin (400-mil)	15	480
F/FA/F28, BXA, XA	28-pin (600-mil)	13	312
FA	32-pin (600-mil)	11	264
F/FA/F40, BQA, MQA, QA	40-pin (600-mil)	9	216

CERPAC

PACKAGE CODE	PIN COUNT	QUANTITIES
		DEVICES PER TUBE
BDA/DA/W	14-pin	145
BFA/FA/W	16-pin	145
BXA/BYA/W	18-pin	100
BSA/SA/W/WB	20-pin	100
BKA/KA/W	24-pin	120
BYA/YA/W	28-pin	50

CERQUAD

PACKAGE CODE	PIN COUNT	QUANTITIES	
		DEVICES PER TRAY	DEVICES PER BOX
KA/K44	44-pin	6	6
KA/K68	68-pin	4	4
KA	84-pin	42	210

LEADLESS CHIP CARRIER

PACKAGE CODE	PIN COUNT	QUANTITIES
		DEVICES PER TUBE
B2A/2A/GA	20-pin	55
B3A/3A/GA/GC1	28-pin	43
YA/YA/GC2	32-pin	35
BUA/MXA/MUA/UA/XA/GA/GC	44-pin	27
BZA/BUA/UA/ZA/GA/GC	68-pin	19

QUANTITIES SHOWN IN GRAY REQUIRE PURCHASE TO BE MADE IN EXACT MULTIPLES OF THAT QUANTITY.

VII. PACKING QUANTITY INFORMATION

T-90-20

PLASTIC DUAL IN-LINE

PACKAGE CODE	PIN COUNT	QUANTITIES	
		DEVICES PER TUBE	DEVICES PER BOX
N/N8	8-pin (300-mil)	50	2000
N/N14/N16	14- 16-pin (300-mil)	25	1000
N	18-pin (300-mil)	20	800
N/N20	20-pin (300-mil)	18	720
N	22-pin (400-mil)	17	544
N/N6	24-pin (600-mil)	15	360
N/N3/N24	24-pin (300-mil)	15	600
N/N24	24-pin (400-mil)	15	480
N/N28	28-pin (600-mil)	13	312
N/N3	28-pin (300-mil)	13	520
N	32-pin (600-mil)	11	264
N/N40	40-pin (600-mil)	9	216
NB (Shrink)	42-pin (600-mil)	12	288
N/N48	48-pin (600-mil)	7	168
N	50-pin (900-mil)	7	112
N/N64	64-pin (900-mil)	5	80

PLASTIC LEADED CHIP CARRIER (PLCC)

PACKAGE CODE	PIN COUNT	QUANTITIES		
		DEVICES PER TUBE	DEVICES PER BOX	DEVICES PER REEL
A	20-pin	46	3680	1000
A/A28	28-pin	37	2368	750
A	32-pin	31	2232	750
A/A44	44-pin	26	1248	500
A/A52	52-pin	23	1012	500
A/A68	68-pin	18	648	250
A/A84	84-pin	15	420	250

QUANTITIES SHOWN IN GRAY REQUIRE PURCHASE TO BE MADE IN EXACT MULTIPLES OF THAT QUANTITY.

VII. PACKING QUANTITY INFORMATION

T-90-20

PLASTIC SMALL OUTLINE (SO)

PACKAGE CODE	PIN COUNT	QUANTITIES		
		DEVICES PER TUBE	DEVICES PER BOX	DEVICES PER REEL
D/D8	8-pin (150-mil)	100	10000	2500
D	8-pin (300-mil)	64	2560	1000 – 13" 700 – 7"
D/D14	14-pin (150-mil)	57	5700	2500
D	16-pin (150-mil)	50	5000	2500
D	16-pin (300-mil)	48	1920	1000
DK(SSOP)	20-pin (170-mil)	75	6750	2500
D	20-pin (300-mil)	38	1520	1000
D/D24	24-pin (300-mil)	32	1280	1000
D	28-pin (300-mil)	27	1080	1000
D	40-pin (VSO-40)	31	1240	1000 – 13" 300 – 7"
D	56-pin (VSO-56)	22	616	1000

QUAD FLAT PACK*

PACKAGE CODE	PIN COUNT	QUANTITIES	
		DEVICES PER TRAY	DEVICES PER BOX
B/B44	44-pin	50	500
B/B44	44-pin	96	480
B	52-pin	119	595
B	80-pin	66	330
B	100-pin	50	250
B	120-pin	24	120
B	120-pin (Philips source)	30	150

* Quad Flat Pack parts require dry pack handling according to EIA Standard - 583.
These parts are identified in part list section with DRY PACK in the Cross Ref Part No field.

QUANTITIES SHOWN IN GRAY REQUIRE PURCHASE TO BE MADE IN EXACT MULTIPLES OF THAT QUANTITY.

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